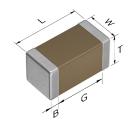
积层贴片陶瓷片式电容器

C1608X5R1E225K080AB

RoHS Reach Halogen Free Pb Free

交货型号	C1608X5R1E225KT****
用途	一般等级
特点	General 一般(~75V)
系列	C1608 [EIA 0603]
状态	量产体制



尺寸			
长度(L)	1.60 mm ± 0.10 mm		
宽度(W)	0.80 mm ± 0.10 mm		
厚度(T)	0.80 mm ± 0.10 mm		
端子宽度(B)	0.20mm Min.		
端子间隔(G)	0.30mm Min.		
推荐焊盘布局(PA)	0.70mm to 1.00mm(Flow Soldering)		
1世存产益4月/月 (FA)	0.60mm to 0.80mm(Reflow Soldering)		
推荐焊盘布局(PB)	0.80mm to 1.00mm(Flow Soldering)		
TE存斥血和内(ID)	0.60mm to 0.80mm(Reflow Soldering)		
推荐焊盘布局(PC)	0.60mm to 0.80mm(Flow Soldering)		
TEAT/PETTIP PU (L C)	0.60mm to 0.80mm(Reflow Soldering)		

电气特性			
电容	$2.2\mu\mathrm{F}\pm10\%$		
额定电压	25VDC		
温度特性	$X5R(\pm 15\%)$		
耗散因数(Max.)	10%		
绝缘电阻 (Min.)	227MΩ		

	其他	
焊接方法	流体	
坪 接刀法	回流	
AEC-Q200	NO NO	
包装形式	纸编带 (180mm卷筒)	
包装个数	4000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

RoHS Reach Halogen Free Pb Free



特性图表(这是参考数据,并不保证产品的特性。)

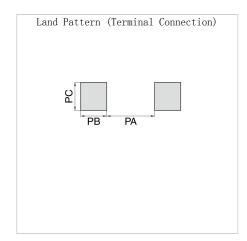
[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

RoHS Reach Halogen Free Pb Free

Associated Images



[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.